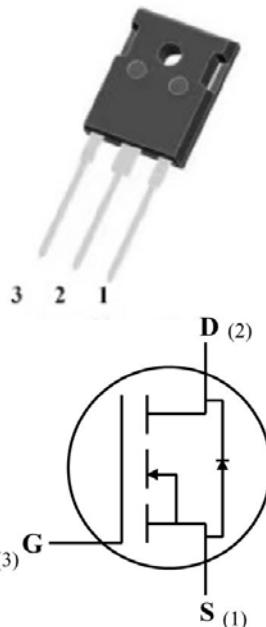




Silicon Carbide Power MOSFET (N-Channel Enhancement)

V_{DS}	1200V
$I_D(25^\circ C)$	24A
$R_{DS(on)}$	120mΩ

**Features**

- High speed switching
- Essentially no switching losses
- Reduction of heat sink requirements
- Maximum working temperature at 175 °C
- High blocking voltage
- Fast Intrinsic diode with low recovery current
- High-frequency operation
- Halogen free, RoHS compliant
- AEC-Q101 qualified

Typical Applications

Typical applications are in power factor correction(PFC), solar inverter, uninterruptible power supply, motor drives, photovoltaic inverter, electric car and charger.

Mechanical Data

- **Package:** TO-247AB
- **Terminals:** Tin plated leads
- **Polarity:** As marked

■Maximum Ratings ($T_c=25^\circ C$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	VALUE	TEST CONDITIONS	NOTE
Device marking code				D2120120NCTGH	
Drain source voltage @ $T_j=25^\circ C$	$V_{DS,max}$	V	1200	$V_{GS}=0 V, I_D=100\mu A$	
Gate source voltage @ $T_j=25^\circ C$	$V_{GS,max}$	V	-10/+25	Absolute maximum values (AC f > 1Hz, duty cycle < 1%)	Note1
Gate source voltage @ $T_j=25^\circ C$	$V_{GS,op}$	V	-5/+20	Recommended operational values	
Continuous drain current @ $T_c=25^\circ C$	I_D	A	24	$V_{GS}=20V, T_c=25^\circ C$	Fig.14
Continuous drain current @ $T_c=110^\circ C$			16.5	$V_{GS}=20V, T_c=110^\circ C$	
Pulse Drain Current	$I_{D,pulse}$	A	65	Limited by t_{pw}	Fig.15
Avalanche energy, Single Pulse	E_{AS}	mJ	625	$V_{DD}=100V, I_D=7A$	
Power Dissipation	P_{TOT}	W	166	$T_c=25^\circ C, T_j = 175^\circ C$	Fig.13
Operating junction and Storage temperature range	T_j, T_{stg}	°C	-55 to +175		
Soldering temperature	T_L	°C	260	1.6mm (0.063") from case for 10s	
Mounting torque	T_M	Nm	1.0	M3 screw Maximum of mounting process: 3	



■ Static Electrical Characteristics (Tc=25°C unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Min.	Typ.	Max.	Test Conditions	Note
Gate threshold voltage	V _{GS(th)}	V		2.95		V _{DS} =V _{GS} , I _D = 10mA	Fig.4, 11
Drain source breakdown voltage	V _{(BR)DSS}	V	1200			V _{GS} =0, I _D =100uA	
Zero gate voltage drain current	I _{DSS}	uA		<1	50	V _{DS} =1200V, V _{GS} = 0V	
				10	500	V _{DS} =1200V, V _{GS} = 0V, Tj= 175°C	
Gate source leakage current	I _{GSS}	nA			250	V _{GS} = 20V, V _{DS} =0V	
Current drain source on-state resistance	R _{DS ON}	mΩ		120	160	V _{GS} =20V, I _D =10A	Fig.3, 5, 6
				200		V _{GS} =20V, I _D =10A, Tj=175°C	
Transconductance	g _f	S		6.2		V _{DS} =12.5V, I _D =60A	

■ Dynamic Electrical Characteristics (Tc=25°C unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Min.	Typ.	Max.	Test Conditions	Note
Input capacitance	C _{iss}	pF		1083		V _{DS} =800V, V _{GS} =0V, Tj=25°C, f=1MHz, V _{AC} = 25mV	Fig.10
Output capacitance	C _{oss}			56			
Reverse capacitance	C _{rss}			8			
C _{oss} stored energy	E _{oss}	uJ		23		V _{DS} =800V, V _{GS} =-5/20V, I _D =10A	Fig.12
Gate source charge	Q _{gs}	nC		14.5			
Gate drain charge	Q _{gd}			29			
Gate charge	Q _g			67			
Internal Gate Resistance	R _{G(int)}	Ω		1.8		f=1MHz, V _{AC} = 25mV	

■ Switching Characteristics (Tc=25°C unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Min.	Typ.	Max.	Test Conditions	Note
Turn on delay time	t _{d(on)}	ns		24		V _{DD} =800V, V _{GS} =0/+20V, I _D =8A, R _L =100Ω, R _{G(ext)} = 10Ω	Fig.17, 18
Rise time	t _r			24			
Turn off delay time	t _{d(off)}			34			
Fall time	t _f			33			
Turn on switching energy	E _{on}	uJ		122		V _{DD} =800V, V _{GS} =0/+20V, I _D =10A, R _{g(ext)} =2.7Ω	Fig.17, 18
Turn off switching energy	E _{off}			41.4			

■Body diode characteristics (T_c=25°C unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Min.	Typ.	Max.	Test Conditions	Note
Diode forward voltage	V _{SD}	V		3.4		V _{GS} =0V, I _{SD} =2.5A	Fig.8
Continuous diode forward current	I _s	A		25		V _{GS} =0V, T _c =25°C	
Reverse recovery time	t _{rr}	nS		53		V _{DS} =400V, V _{GS} =0V, I _{SD} =10A, di/dt=300A/uS	
Reverse recovery charge	Q _{rr}	nC		63			
Peak reverse recovery current	I _{rrm}	A		2.25			

Note 1: When using SiC Body Diode the maximum recommended V_{GS} = -5V

■Thermal Characteristics (T_a=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Value
Thermal resistance	R _{θJ-C}	°C /W	0.9

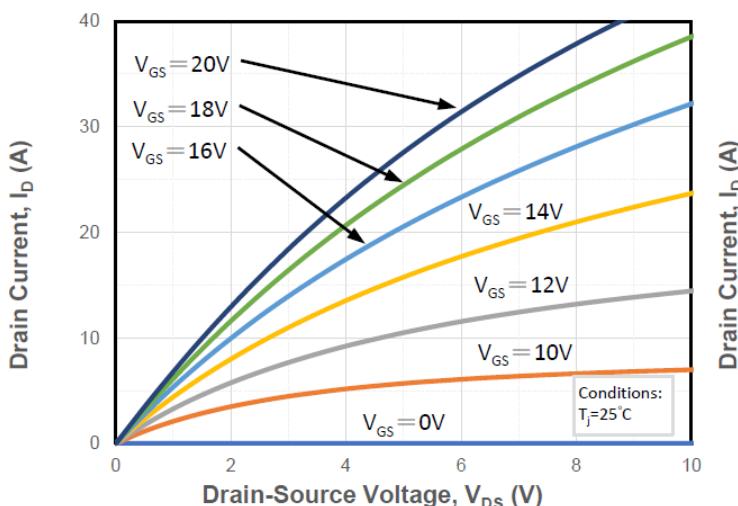
■Typical Characteristics


Figure 1. Output Characteristics T_j = 25°C

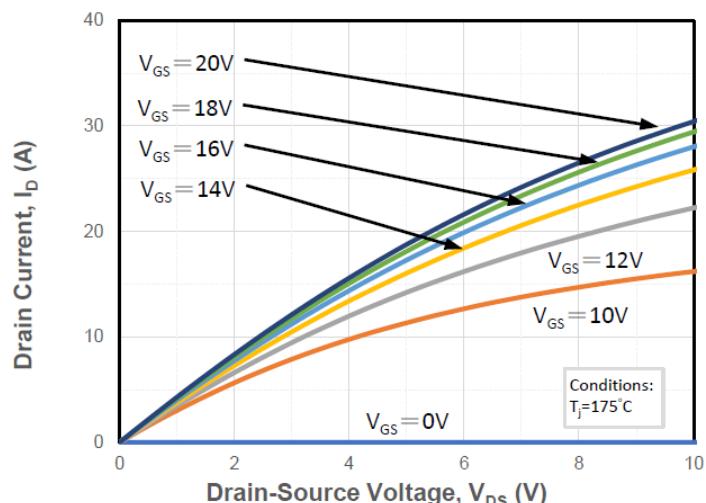


Figure 2. Output Characteristics T_j = 175°C

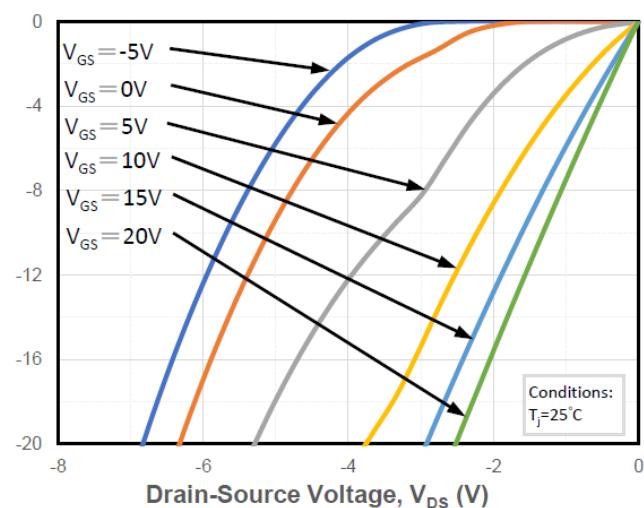
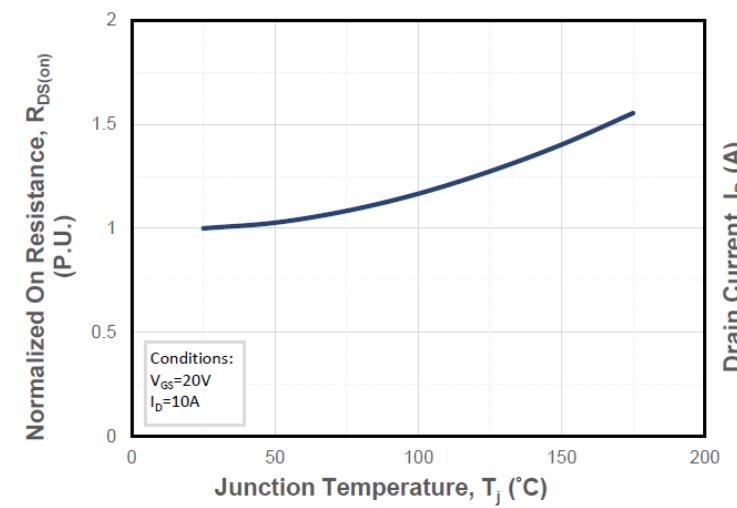
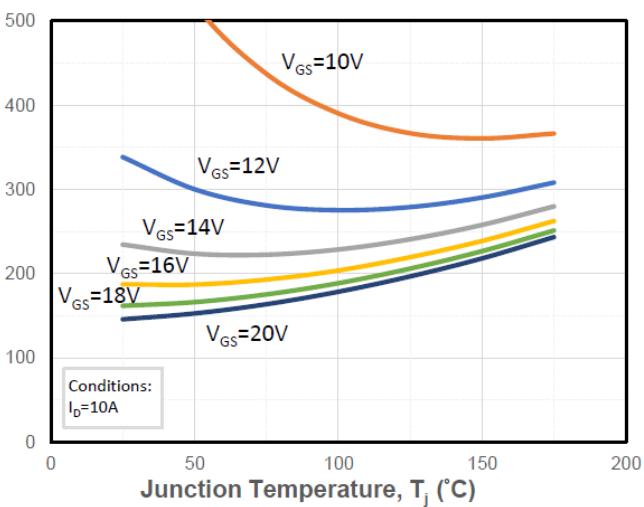
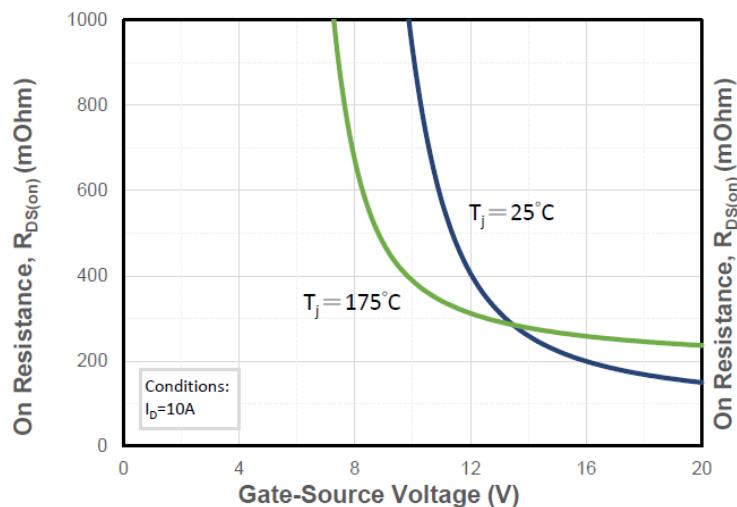
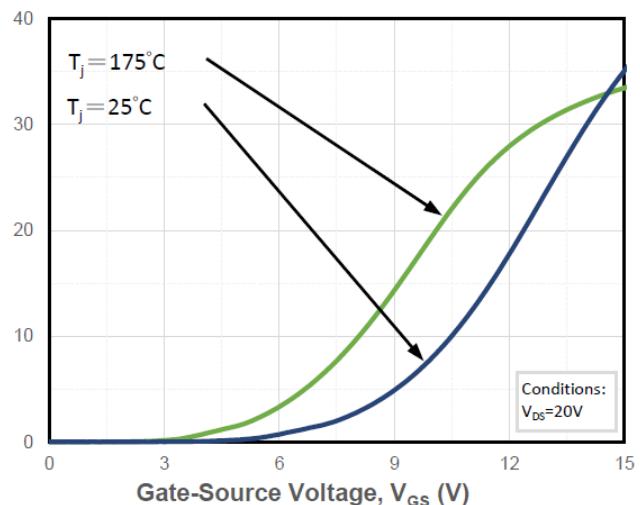
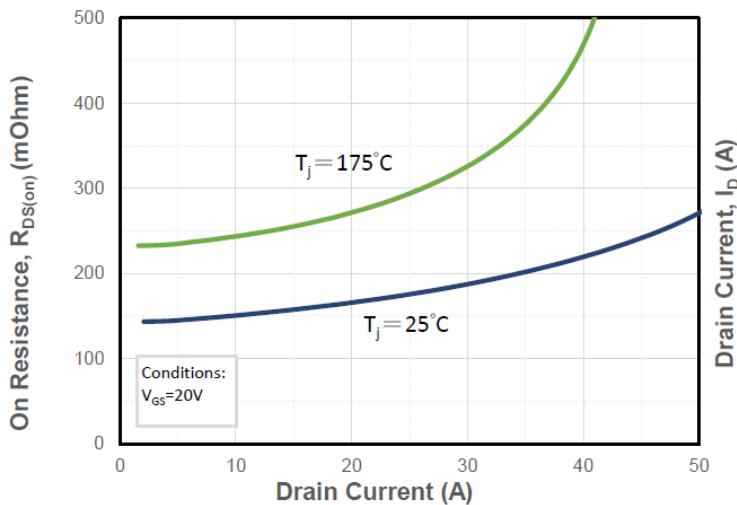


Figure 7. Normalized On-Resistance vs. Temperature

Figure 8. Reverse Output Characteristics at $T_j = 25^\circ\text{C}$

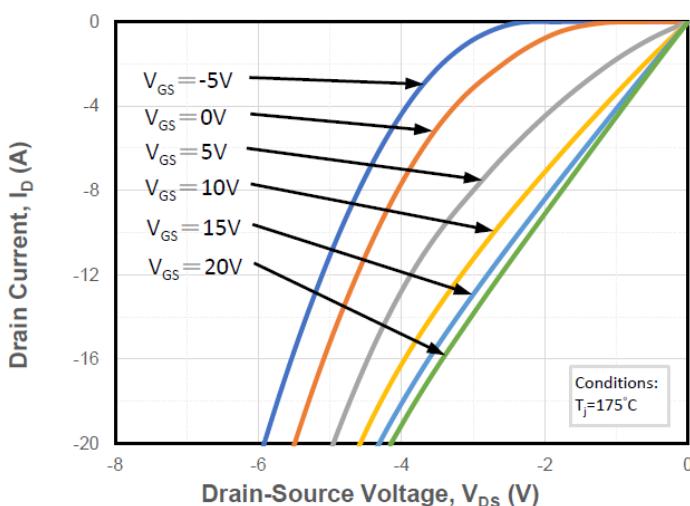


Figure 9. Reverse Output Characteristics at $T_j = 175^\circ\text{C}$

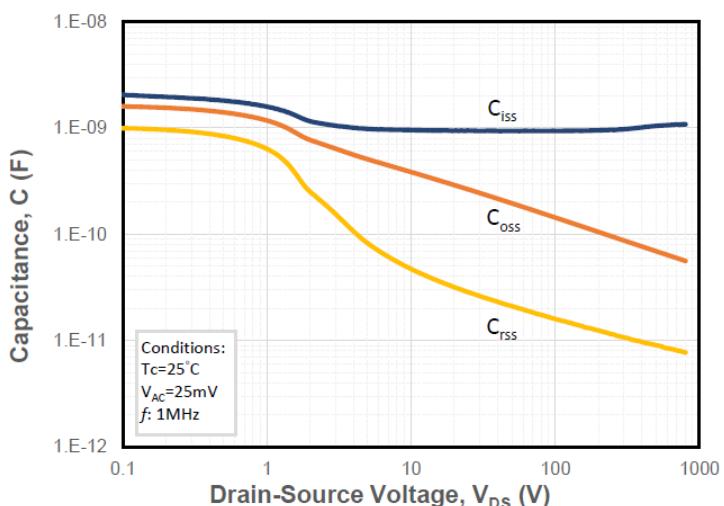


Figure 10. Capacitances vs. Drain to Source Voltage

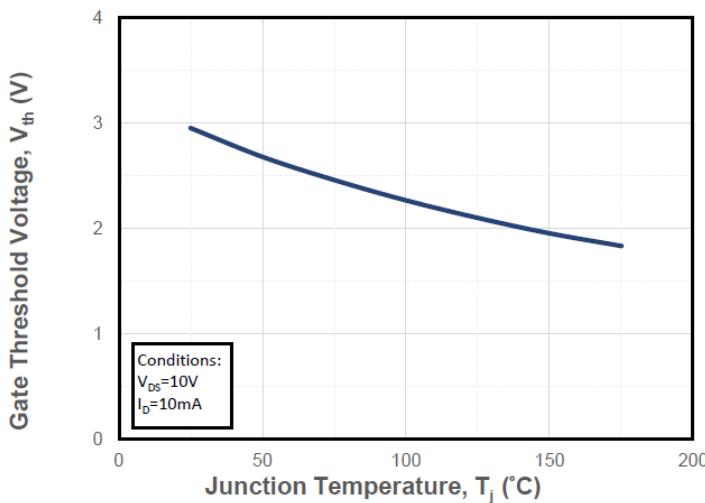


Figure 11. Threshold voltage vs. temperature

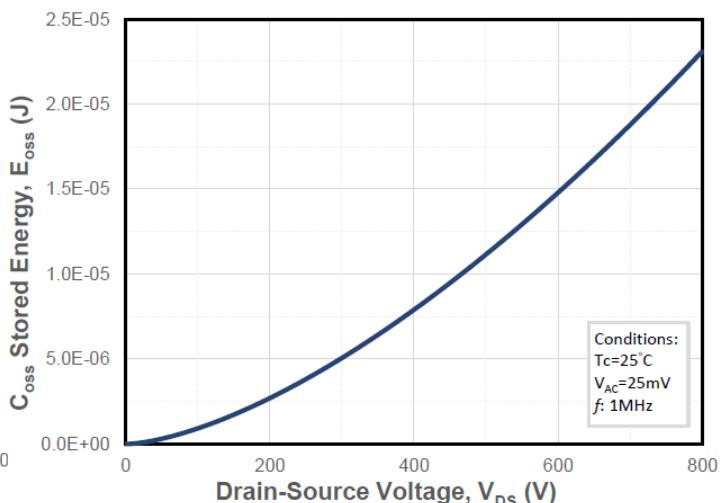


Figure 12. Output Capacitor Stored Energy

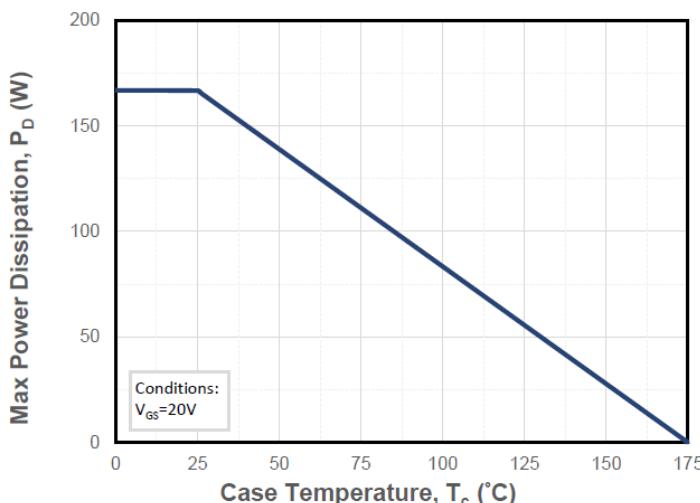


Figure 13. Maximum Power Dissipation Derating vs. Case Temperature

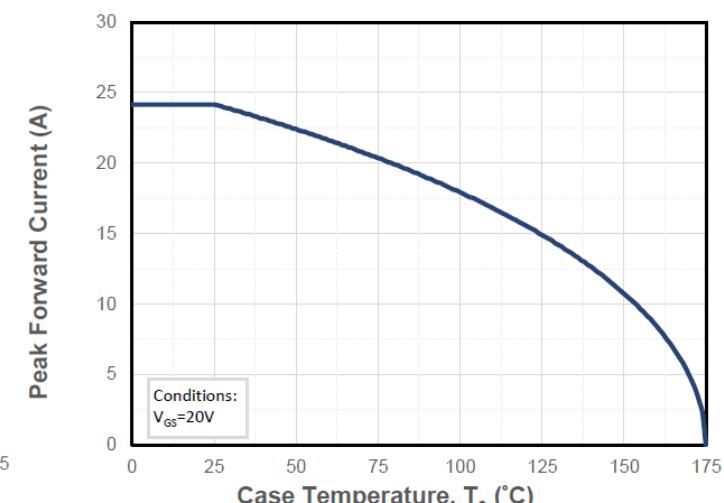


Figure 14. Drain Current Derating vs. Case Temperature

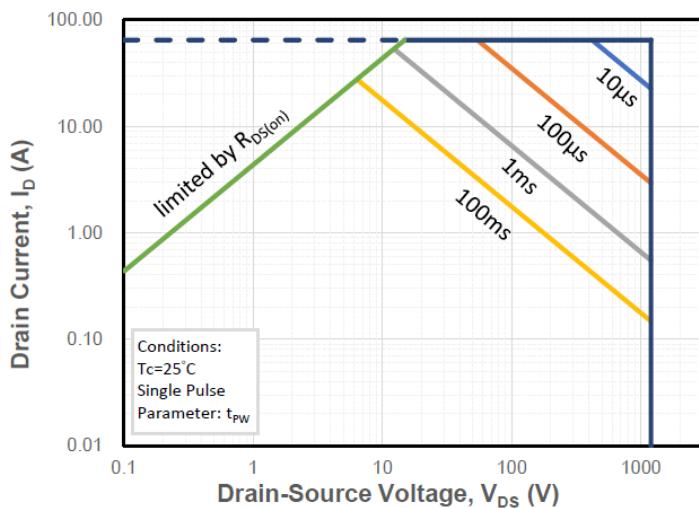


Figure 15. Safe Operating Area

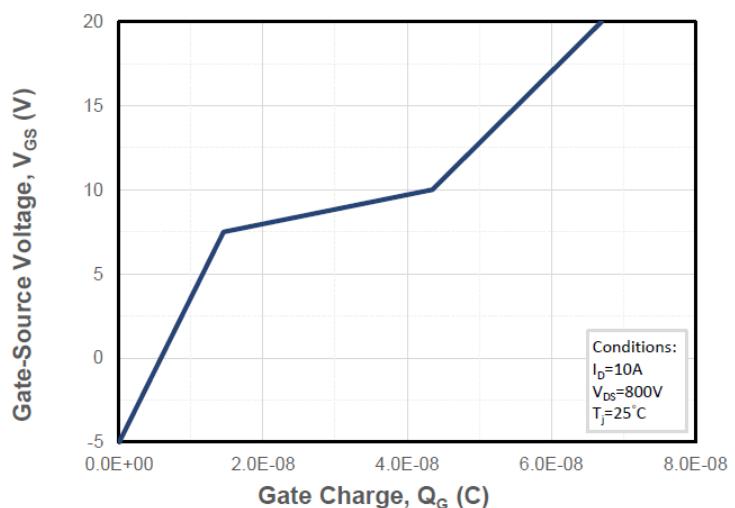


Figure 16. Gate Charge Characteristics

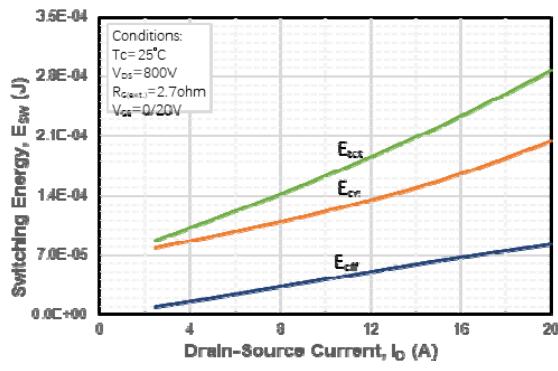


Figure 17. Clamped Inductive Switching Energy vs. Drain Current

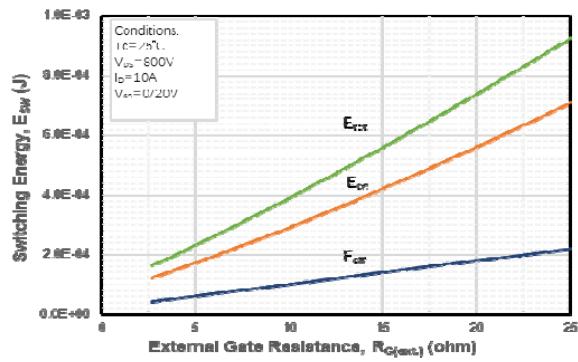


Figure 18. Clamped Inductive Switching Energy vs. External Gate Resistor ($R_{G(ext)}$)

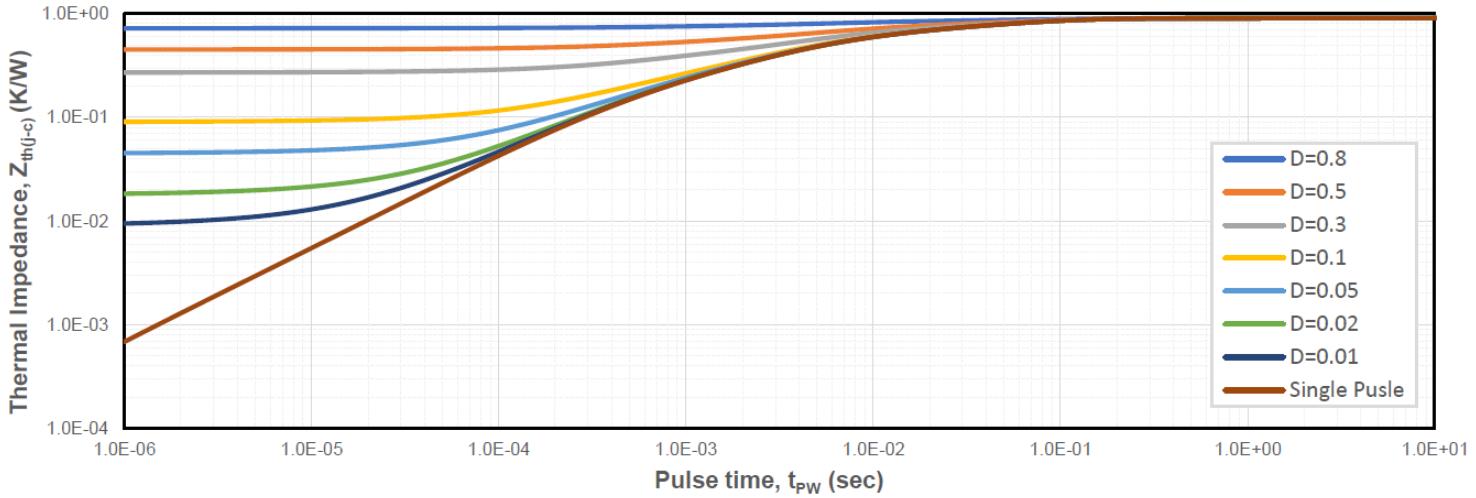


Figure 19. Transient Junction to Case Thermal Impedance

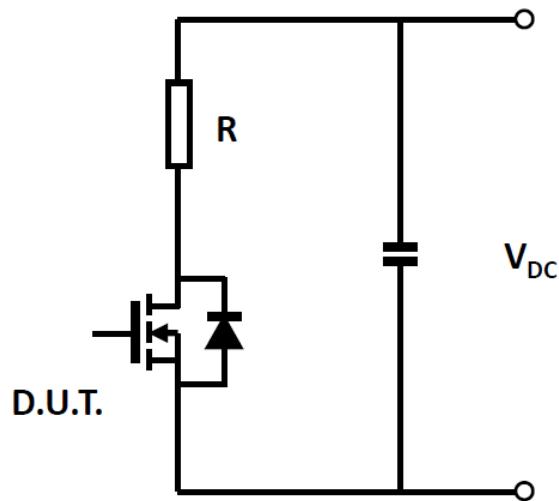


Figure 20. Schematic of Resistive Switching

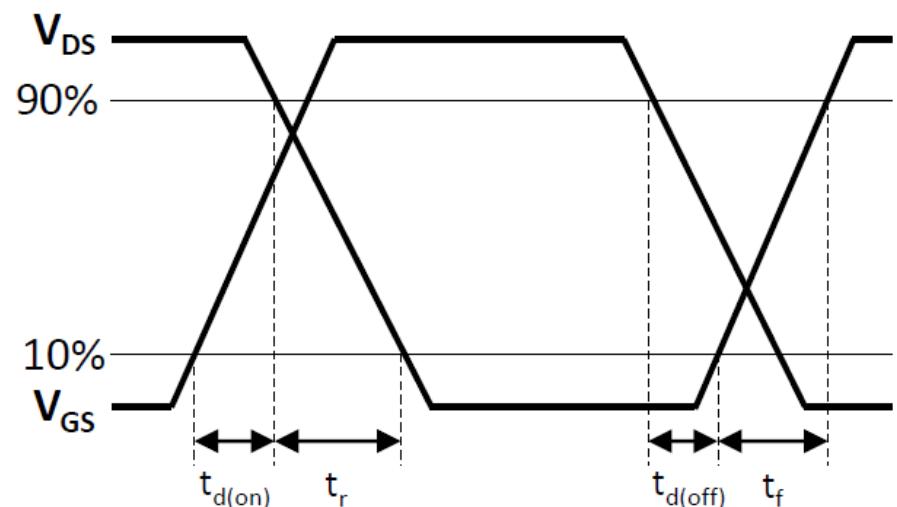
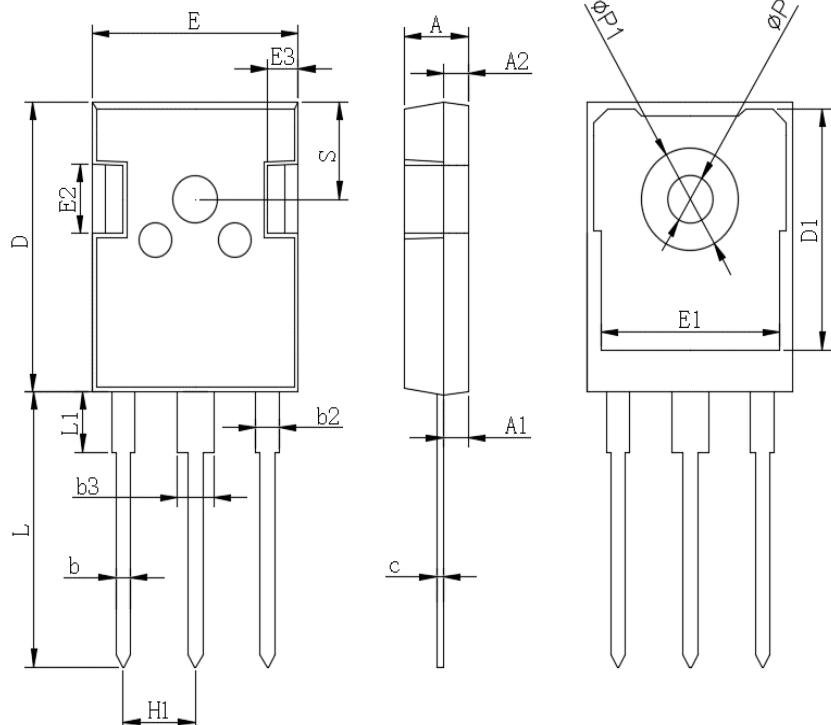


Figure 21. Switching Times Definition



■Outline Dimensions

TO-247AB



TO-247AB		
Dim	Min	Max
A	4.80	5.20
A1	2.21	2.61
A2	1.85	2.15
b	1.0	1.4
b2	1.91	2.21
C	0.5	0.7
D	20.70	21.30
D1	16.25	16.85
E	15.50	16.10
E1	13.0	13.6
E2	4.80	5.20
E3	2.30	2.70
L	19.62	20.22
L1	-	4.30
ΦP	3.40	3.80
ΦP1	-	7.30
S	6.15TYP	
H1	5.44TYP	
b3	2.80	3.20



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